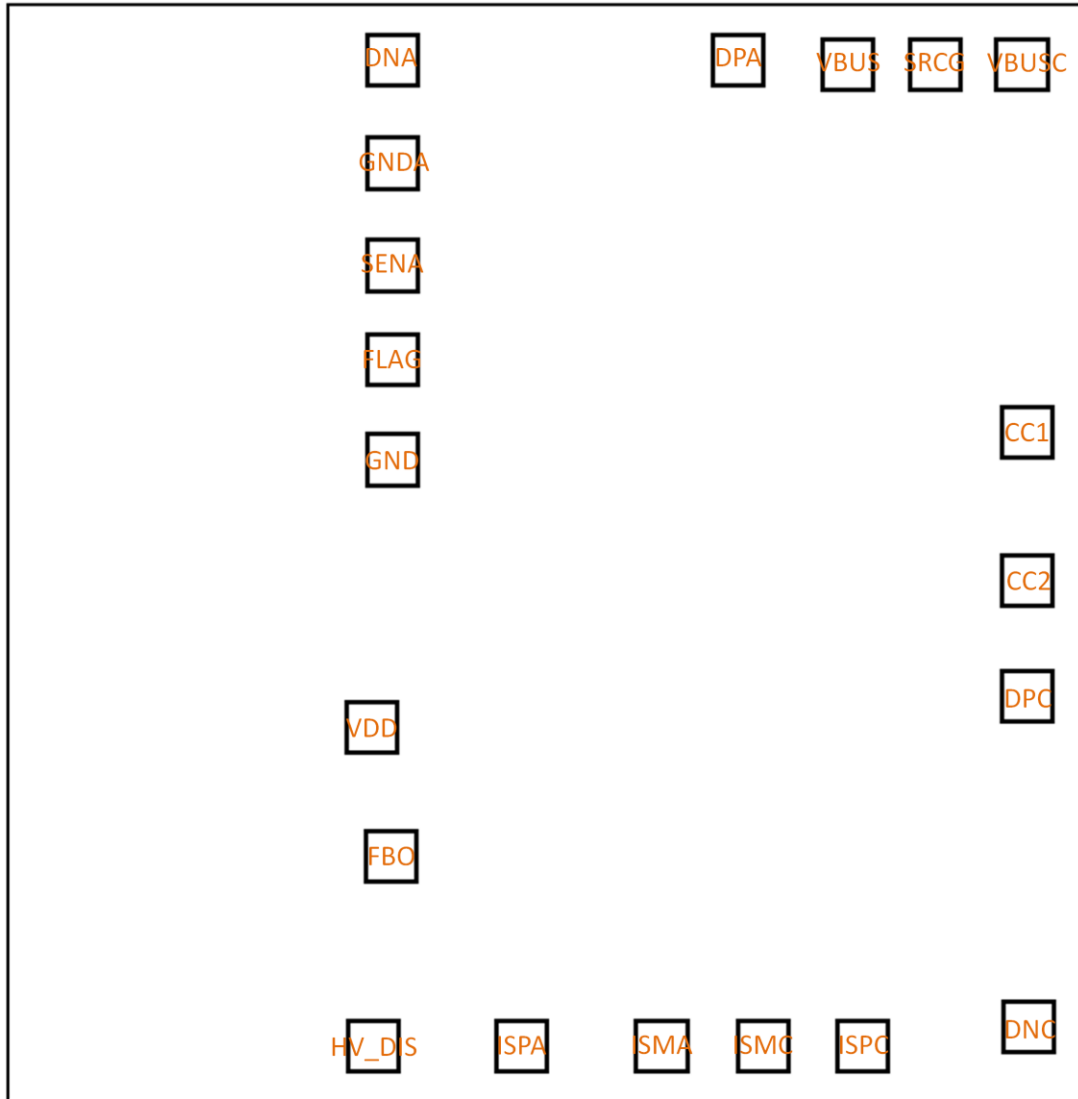




| | | | | | | | | | |
|------|--|----------------|---------|---|-----|--|----------------|---------|----|
| ISMC | | (298.8,-681.3) | (70,70) | 9 | DNA | | (-212.6,682.3) | (70,70) | 19 |
| | | | | | | | | | |

Bond Pad LAYOUT of Chip

附件一





Brief 打線示意圖

附件二

